Product Change Notification / MFOL-26VGNH622

Date:

23-Aug-2022

Product Category:

Switching Regulators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4613 Final Notice: Qualification of Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site for Die#2, Die#3 and EME-G700LA as a new mold compound material for selected MIC2851xx device families available in 32L VQFN (6x6x0.9mm) package at ASE assembly site.

Affected CPNs:

MFOL-26VGNH622_Affected_CPN_08232022.pdf
MFOL-26VGNH622_Affected_CPN_08232022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site for Die#2, Die#3 and EME-G700LA as a new mold compound material for selected MIC2851xx device families available in 32L VQFN (6x6x0.9mm) package at ASE assembly site.

Pre and Post Change Summary:

Fab location change for Die # 2 and Die # 3 only applies for CPNs below:

MIC28514T-E/PHA, MIC28514T-E/PHAVAO, MIC28515T-E/PHA, and MIC28515T-E/PHAVAO

A separate PCN (ALAN-22WDFU453) was issued for other products.

		Pre Change	Post Change
Fabrication Location	Die # 1	Microchip Technology Colorado (MCSO)	Microchip Technology Colorado (MCSO)
	Die # 2	MaxPower Semiconductor (MAPW)	Microchip Technology Tempe - Fab 2 (TMGR)
	Die # 3	MaxPower Semiconductor (MAPW)	Microchip Technology Tempe - Fab 2 (TMGR)
Wafer Size	Die # 1	6 inches	6 inches
	Die # 2 and Die # 3	8 inches	8 inches

Mold compound change only applies for CPNs below:

MIC28514T-E/PHA, MIC28515T-E/PHA, MIC28516T-E/PHA, and MIC28517T-E/PHA

	Pre Change	Post Change
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)
Wire Material	CuPdAu	CuPdAu
Die Attach Material	CDF625P8C8 (Controller die) – DAF 84-1 LMISR4 (FET die) - Paste	CDF625P8C8 (Controller die) – DAF 84-1 LMISR4 (FET die) - Paste
Molding Compound Material	EME-G631H	EME-G700LA
Lead-Frame Material	C194	C194

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site for Die#2, Die#3 and EME-G700LA as a new mold compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: September 30, 2022 (date code: 2240)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2022					September 2022			
Workweek	32	33	34	35	36	37	38	39	40
Qual Report Availability				x					
Final PCN Issue Date				x					
Estimated Implementation Date									x

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: August 23, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_MFOL-26VGNH622_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC28514T-E/PHA
MIC28514T-E/PHAVAO
MIC28515T-E/PHA
MIC28515T-E/PHAVAO
MIC28516T-E/PHA
MIC28517T-E/PHA